

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention	[METHOD OF FORMING BOND MICROSTRUCTURE]				
Application Number :					
Date :					
First Named Applicant:		Mr. CHENG-HENG KAO			
Attorney Docket Number:		12476-US-PA			
TOTAL FEE AUTHORIZED \$ 497					
Patent fees are subject to annual revisions on or about October 1st of each year.					
Filing as small entity					
BASIC FILING FEE					
Fee Description		Fee Code	Amount \$	Fee Paid \$	
Utility Filing Fee		2001	385	385	
				Subtotal For Basic Filing Fees: \$ 385	
EXTRA CLAIM FEES					
Fee Description		Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 28		8	2202	9	72
Independent Claims : 2		0	2201	43	0
				Subtotal For Extra Claims Fees: \$ 72	
ASSIGNMENT FEES					
Fee Description		Property Number	Quantity	Fee Code	Amount \$
Recording Each Patent Assignment Per Property Fee		00000000	1	8021	40
				Subtotal For Additional Fees: \$40	
AUTHORIZED BILLING INFORMATION					
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:					
Credit account number:		1007			
Expiration Date (YYYYMMDD):		2005-12-31			
Authorized name:		YEH, WEN-HUNG			
Billing address:		99999			